



Material Content Data Sheet



Sales Product Name				IPD100N06S4-03		Issued		20. July 2018	
MA#				MA001038612					
Package				PG-TO252-3-11		Weight*		378.00 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.184	1.37	1.37	13714	13714	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		570		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		171		
	non noble metal	copper	7440-50-8	215.017	56.87	56.95	568824	569565	
wire	non noble metal	aluminium	7429-90-5	52.643	13.93	13.93	139265	139265	
encapsulation	organic material	carbon black	1333-86-4	0.779	0.21		2060		
	plastics	epoxy resin	-	13.627	3.61		36051		
	inorganic material	silicondioxide	60676-86-0	63.465	16.79	20.61	167896	206007	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9894	9894	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		240		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	241	
solder	noble metal	silver	7440-22-4	0.099	0.03		263		
	non noble metal	tin	7440-31-5	0.079	0.02		210		
	non noble metal	lead	7439-92-1	3.796	1.00	1.05	10041	10514	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.07	5.08	50734	50800	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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